

TEF1001 TRM

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Overview

The Trenz Electronic TEF1001 FPGA board is a PCI Express form factor card integrating the Xilinx Kintex-7 XC7K160T, XC7K325T or XC7K410T FPGA SoC. The FPGA-board is designed for high system resources and intended for use in applications with high demands on system performance and throughput. To extend the board with standard DDR3 SDRAM memory module, there is a 204-pin SODIMM socket with 64bit databus width on the board present. Highspeed data transmission is enabled by the 4 lane PCIe Gen 2 interface.

The board offers a HPC (High Pin Count) ANSI/VITA 57.1 compatible FMC interface connector for standard FPGA Mezzanine cards and modules. Other interface connectors found on-board include JTAG for accessing FPGA and on-board System Controller CPLD.

The TEF1001 FPGA board is intended to be used as add-on card in a PCIe 2.0 or higher capable host system to meet the power supply requirements.

Refer to <http://trenz.org/tef1001-info> for the current online version of this manual and other available documentation.

Key Features

- Xilinx Kintex-7 XC7K160T, XC7K325T or XC7K410T FPGA SoC
- Large number of configurable I/Os are provided via HPC FMC connector
 - 4 GTX high-performance transceiver
 - 2x MGT transceiver clock inputs
 - 160 FPGA I/O's (80 LVDS pairs)
- On-board high-efficiency switch-mode DC-DC converters
- Lattice MachXO2 LCMXO2-1200HC System Controller CPLD
- 10x User LEDs
- PCI Express x8 connector with 4 lane PCIe Gen 2 interface
- ANSI Vita 57.1 FMC High Pin Count (HPC) connector
- DDR3 SODIMM SDRAM with ECC socket with 64bit databus width
- 256Mbit (32MByte) Quad SPI Flash memory (for configuration and operation) accessible through:
 - FPGA
 - JTAG port (SPI indirect, bus width x4)
- FPGA configuration through:
 - JTAG connector
 - Quad SPI Flash memory
- Clocking
 - Si5338 programmable quad PLL clock generator - 4 outputs for MGT and PL clocks
 - 200MHz oscillator for DDR3 bank
- System management and power sequencing

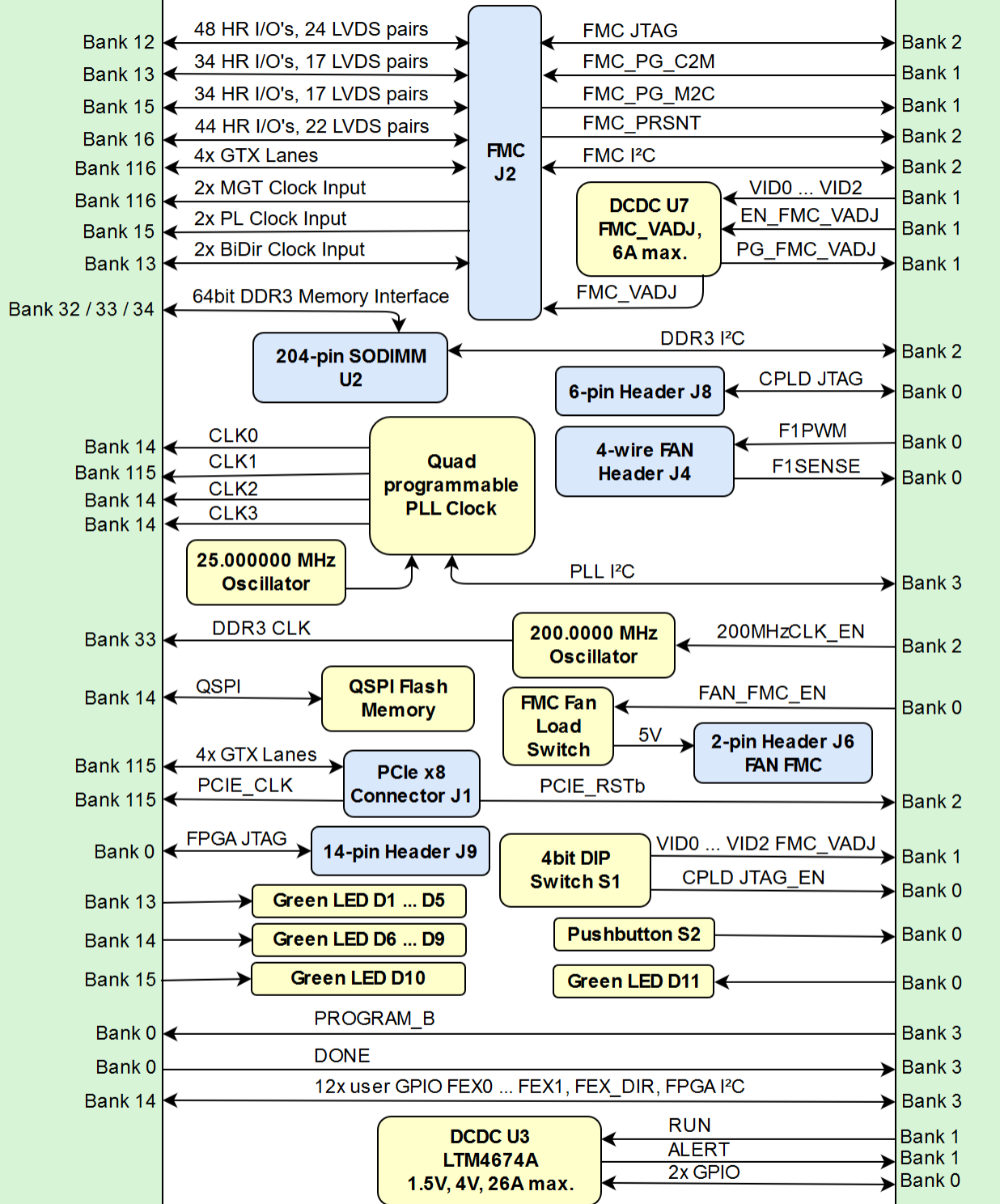
Additional assembly options are available for cost or performance optimization upon request.

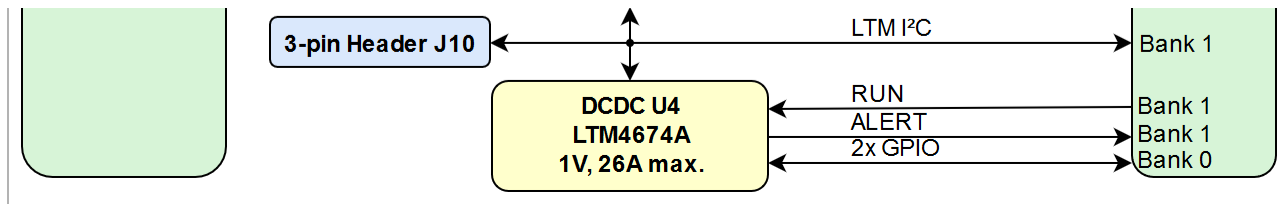
Block Diagram

TEF1001-02

**Xilinx Kintex
XC7K FPGA SoC**

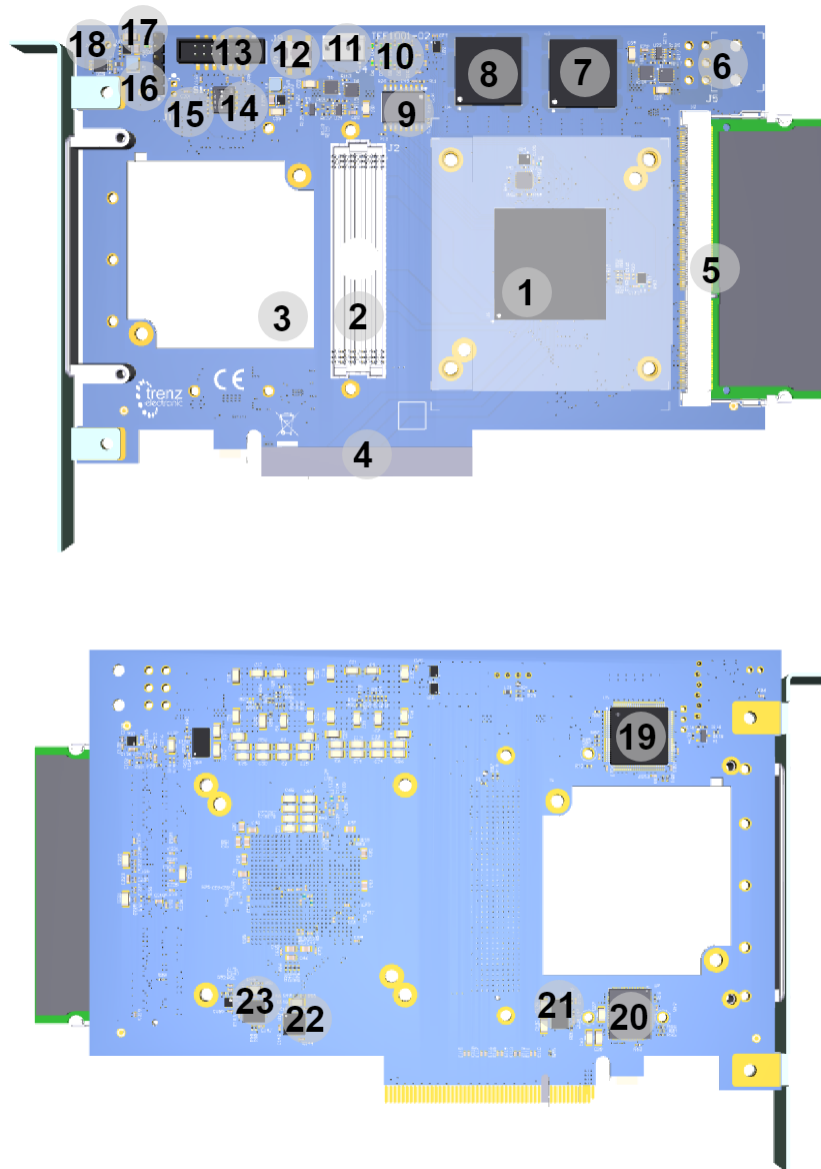
SC CPLD





TEF1001-02 block diagram

Main Components



TEF1001-02 main components

1. Xilinx Kintex XC7K-2FBG676I FPGA SoC, U6
2. ANSI/VITA 57.1 compliant FMC HPC connector, J2
3. Cooling fan 5VDC M1 (45X5MM, 0.7W, 1.06CFM), M1
4. PCIe x8 connector, J1
5. DDR3 SODIMM 204-pin socket, U2
6. 6-pin 12V power connector, J5
7. Step-down DC-DC converter @1.5V and @4V (LT LTM4676A), U3
8. Step-down DC-DC converter @1.0V (LT LTM4676A), U4
9. 256 Mbit Quad SPI Flash Memory (Micron N25Q256A), U12

10. 10x Green user LEDs connected to FPGA, D1 ... D10
11. 4-wire PWM fan connector, J4
12. User button, S2
13. FPGA JTAG connector, J9
14. 4bit DIP switch, S1
15. I²C header for LTM4676A DC-DC converter, J10
16. System Controller CPLD JTAG header, J8
17. 1x Green LED connected to SC CPLD, D11
18. 2-pin 5V FAN header, J6
19. System Controller CPLD (Lattice Semiconductor LCMXO2-1200HC), U5
20. 6A PowerSoC DC-DC converter @FMC_VADJ (Altera EN5365QI), U7
21. 4A PowerSoC DC-DC converter @3.3V (3V3FMC) (Altera EN6347QI), U15
22. LDO converter @1.2V (MGTAVTT_FPGA) (TI TPS74401RGW), U17
23. LDO converter @1.0V (MGTAVCC_FPGA) (TI TPS74401RGW), U18
24. 4A PowerSoC DC-DC converter @1.8V (Altera EN6347QI), U7

Initial Delivery State

Storage device name	Content	Notes
Si5338A OTP Area	not programmed	-
SPI Flash OTP Area	Empty, not programmed	Except serial number programmed by flash vendor
SPI Flash Quad Enable bit	Programmed	-
SPI Flash main array	demo design	-
HyperFlash Memory	not programmed	-
eFUSE USER	Not programmed	-
eFUSE Security	Not programmed	-

Initial delivery state of programmable on-board devices

Control Signals

To get started with TEF1001 board, some basic control signals are essential and are described in the following table:

Control signal	Switch / Button / LED / Pin	Signal Schematic Names	Connected to	Functionality	Notes
SC CPLD JTAG Enable	DIP switch S1-1	JTAG_EN	SC CPLD U5, pin 82	ON-position: SC CPLD U5 JTAG interface enabled	-
BOOT Mode	FPGA bank 0, pins T5, T2, P5	-	Pin T5 (M0): 1V8 Pin T2 (M1): GND Pin P5 (M2): GND	Hard-wired Boot Mode	By default the configuration mode pins M[2:0] of the FPGA are set to QSPI mode (Master SPI)
Global Reset input	Push Button S2	S2	SC CPLD U5, pin 77	Manual reset from user	-
FMC_VADJ voltage selection	DIP switches S1-2, S1-3, S1-4	VID0_FMC_VADJ_CTRL ... VID2_FMC_VADJ_CTRL	SC CPLD U5, pins 71, 63, 62	sets adjustable voltage 'FMC_VADJ' for FMC connector	DIP-switch states forwarded by SC CPLD U5 to DC-DC U7. Refer to section Configuration DIP-switch for more details.

TEF1001 Control Signals

Signals, Interfaces and Pins

FMC HPC Connector

I/O signals and interfaces connected to the FPGA SoCs I/O bank and FMC connector J2:

Interfaces	I/O Signal Count	LVDS-pairs count	Connected to	VCCO bank Voltage	Notes
I/O	48	24	FPGA Bank 12 HR	FMC_VADJ	Bank voltage FMC_VADJ is supplied by DC-DC converter U7
	34	17	FPGA Bank 13 HR	FMC_VADJ	
	34	17	FPGA Bank 15 HR	FMC_VADJ	
	44	44	FPGA Bank 16 HR	VIO_B_FMC	Bank voltage VIO_B_FMC is supplied by FMC connector J2
I²C	2	-	SC CPLD U5, Bank 2, pin 48, 49	-	FMC connector J2 is hardware programmed to I²C address 0x50
JTAG	5	-	SC CPLD U5, Bank 2, pin 27, 28, 331, 32 ,36	3.3V	4 JTAG pins with additional signal 'TRST'
MGT	-	8 (4 x RX/TX)	Bank 116 GTX	-	4x MGT lanes
Clock Input	-	2	Bank 116 GTX	-	2x Reference clock input to MGT bank
Control Signals	3	-	SC CPLD U5, Bank 1, pin 68, 69 ,70	3.3V	'FMC_PG_C2M', 'FMC_PG_M2C', 'FMC_PRSNT_M2C_L'

FMC connector J2 interfaces

For detailed information about the pin out, please refer to the [Pin-out Tables](#).

FMC connector J2 MGT Lanes:

MGT Lane	Bank	Type	Signal Schematic Name	FMC Connector Pin	FPGA Pin
0	116	GTX	- DP3_M2C_P - DP3_M2C_N - DP3_C2M_P - DP3_C2M_N	- J2-A10 - J2-A11 - J2-A30 - J2-A31	- MGTXRXP0_116, G4 - MGTXRXN0_116, G3 - MGTXTXP0_116, F2 - MGTXTXN0_116, F1
1	116	GTX	- DP2_M2C_P - DP2_M2C_N - DP2_C2M_P - DP2_C2M_N	- J2-A6 - J2-A7 - J2-A26 - J2-A27	- MGTXRXP1_116, E4 - MGTXRXN1_116, E3 - MGTXTXP1_116, D2 - MGTXTXN1_116, D1
2	116	GTX	- DP1_M2C_P - DP1_M2C_N - DP1_C2M_P - DP1_C2M_N	- J2-A2 - J2-A3 - J2-A22 - J2-A23	- MGTXRXP2_116, C4 - MGTXRXN2_116, C3 - MGTXTXP2_116, B2 - MGTXTXN2_116, B1
3	116	GTX	- DP0_M2C_P - DP0_M2C_N - DP0_C2M_P - DP0_C2M_N	- J2-C6 - J2-C7 - J2-C2 - J2-C3	- MGTXRXP3_116, B6 - MGTXRXN3_116, B5 - MGTXTXP3_116, A4 - MGTXTXN3_116, A3

FMC connector J2 MGT lanes

FMC connector J2 reference clock sources:

Signal Schematic Name	Connected to	FMC Connector Pin	FPGA Pin	Notes
- GBTCLK0_M2C_P - GBTCLK0_M2C_N	MGT bank 116	J2-D4 J2-D5	MGTREFCLK0P_116, D6 MGTREFCLK0N_116, D5	Supplied by attached FMC module
- GBTCLK1_M2C_P - GBTCLK1_M2C_N	MGT bank 116	J2-B20 J2-B21	MGTREFCLK1P_116, F6 MGTREFCLK1N_116, F5	Supplied by attached FMC module

FMC connector J2 clock signal input

FMC connector J2 VCC/VCCIO:

Available VCC/VCCIO	FMC Connector Pin	Source	Notes
3V3FMC	J2-D36 J2-D38 J2-D40 J2-C39	DCDC U15, max. current: 4A	Enable by SC CPLD U5, bank 1, pin 60 Signal: 'EN_3V3FMC'
3V3	J2-D32	LDO U9, max. current: 0.5A	not dedicated for FMC connector
12V	J2-C35 J2-C37	external source through ATX main power connector	-
FMC_VADJ	J2-H40 J2-G39 J2-F40 J2-E39	DCDC U7, max. current: 6A	Enable by SC CPLD U5, bank 1, pin 51 Signal: 'EN_FMC_VADJ' set voltage FMC_VADJ by DIP switch S1

FMC connector J2 available VCC/VCCIO

FMC connector J2 Cooling Fan:

Fan Designator	Enable Signal	Notes
M1	Enable by SC CPLD U5, bank 0, pin 78 Signal: 'FAN_FMC_EN'	-

FMC connector J2 cooling fan

PCI Express Interface

The TEF1001 FPGA board is a PCI Express card designed to fit into systems with PCI Express x8 slots and has a data transmission capability which meets PCIe Gen. 2 with 4 GTX lanes routed to the PCIe interface.

Following table lists lane number, MGT bank number, transceiver type, signal schematic name, connector and FPGA pins connection:

Lane	Bank	Type	Signal Name	PCIe Connector Pin	FPGA Pin
0	115	GTX	- PER3_P - PER3_N - PET3_P - PET3_N	- J1-A29 - J1-A30 - J1-B27 - J1-B28	- MGTXTXP0_115, P2 - MGTXTXN0_115, P1 - MGTXRXPO_115, R4 - MGTXRXN0_115, R3

1	115	GTX	• PER2_P • PER2_N • PET2_P • PET2_N	• J1-A25 • J1-A26 • J1-B23 • J1-B24	• MGTTXTP1_115, M2 • MGTXTXN1_115, M1 • MGTXRX1_115, N4 • MGTXRXN1_115, N3
2	115	GTX	• PER1_P • PER1_N • PET1_P • PET1_N	• J1-A21 • J1-A22 • J1-B19 • J1-B20	• MGTTXTP2_115, K2 • MGTXTXN2_115, K1 • MGTXRX2_115, L4 • MGTXRXN2_115, L3
3	115	GTX	• PER0_P • PER0_N • PET0_P • PET0_N	• J1-A16 • J1-A17 • J1-B14 • J1-B15	• MGTTXTP3_115, H2 • MGTXTXN3_115, H1 • MGTXRX3_115, J4 • MGTXRXN3_115, J3

GTX lanes routed to the PCIe interface

PCIe	Signal Schematic Name	Connected to	PCIe connector pin	FPGA Pin	Notes
J1	• PCIE_CLK_P • PCIE_CLK_N	MGT bank 115	J1-A13, REFCLK+ J1-A14, REFCLK-	MGTREFCLK1P_115, K6 MGTREFCLK1N_115, K5	External clock supplied by PCIe interface

PCIe reference clock sources

JTAG Connectors

There are two JTAG connectors J8 and J9 available on the TEF1001 board:

JTAG Interface	Signal Schematic Name	JTAG Connector Pin	Connected to
CPLD JTAG VCCIO: 3.3V Connector: J8	CPLD_JTAG_TMS	J8-1	SC CPLD, bank 0, pin 90
	CPLD_JTAG_TDI	J8-2	SC CPLD, bank 0, pin 94
	CPLD_JTAG_TDO	J8-3	SC CPLD, bank 0, pin 95
	CPLD_JTAG_TCK	J8-4	SC CPLD, bank 0, pin 91
FPGA JTAG VCCIO: 1.8V Connector: J9	FPGA_JTAG_TMS	J9-4	FPGA, bank 0, pin N9
	FPGA_JTAG_TCK	J9-6	FPGA, bank 0, pin M8
	FPGA_JTAG_TDO	J9-8	FPGA, bank 0, pin N8
	FPGA_JTAG_TDI	J9-10	FPGA, bank 0, pin L8

JTAG interface signals

FAN Connectors

The TEF1001 board offers one FAN connector for cooling the FPGA device and one built-in FAN for the FMC modules.

Connector	Signal Schematic Names	Connected to	Notes
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4-Wire PWM FAN connector J4, 12V power supply	'F1SENSE', pin J4-3 'F1PWM', pin J4-4	SC CPLD U5, pin 99 SC CPLD U5, pin 98	FPGA cooling FAN can be controlled via I ² C interface from FPGA, see current SC CPLD firmware
2-pin FAN connector J6, 5V power supply with TPS2051 Load Switch U25	'FAN_FMC_EN', (Load Switch U25, pin 4)	SC CPLD U5, pin 78	FMC cooling FAN

FAN connectors

On-board Peripherals

System Controller CPLD

The System Controller CPLD (U5) is provided by Lattice Semiconductor LCMXO2-256HC (MachXO2 Product Family). The SC-CPLD is the central system management unit where essential control signals are logically linked by the implemented logic in CPLD firmware, which generates output signals to control the system, the on-board peripherals and the interfaces. Interfaces like JTAG and I²C between the on-board peripherals and to the FPGA module are by-passed, forwarded and controlled by the System Controller CPLD.

Other tasks of the System Controller CPLD are the monitoring of the power-on sequence and to display the programming state of the FPGA module.

For detailed function of the pins and signals, the internal signal assignment and the implemented logic, look to the [Wiki reference page](#) of the board's SC CPLD or into its bitstream file.. Table below lists the SC CPLD I/O pins with their default configuration:

SC CPLD U5 Pins and Interfaces	Connected to	Function	Notes
200MHZCLK_EN	Oscillator U1, pin 1	Oscillator U1 control line	enables 200.0000MHz oscillator U1
BUTTON	Push Button S2	user	Reset Button
CPLD_JTAG_TDO	header J8, pin 3	SC CPLD JTAG interface	SC CPLD JTAG interface enabled when DIP-switch S1-1 in ON-position
CPLD_JTAG_TDI	header J8, pin 2		
CPLD_JTAG_TCK	header J8, pin 4		
CPLD_JTAG_TMS	header J8, pin 1		
JTAG_EN	DIP switch S1-1		
DDR3_SCL	SO-DIMM U2. pin 202	I ² C bus of DDR3 SO-DIMM	I ² C interface connected to FPGA
DDR3_SDA	SO-DIMM U2. pin 200		
PLL_SCL	Si5338 U13, pin 12	I ² C bus of Si5338 quad clock PLL	I ² C interface connected to FPGA
PLL_SDA	Si5338 U13, pin 19		
PCIE_RSTb	PCle J1, pin A11	PCle reset input	refer to current SC CPLD firmware for functionality
FEX_DIR / FEX0 ... FEX11	FPGA bank 14	user GPIO	refer to current SC CPLD firmware for functionality
F1PWM	FAN connector J4, pin 4	FPGA FAN control	refer to current SC CPLD firmware for functionality
F1SENSE	FAN connector J4, pin 3		
FAN_FMC_EN	Load Switch U25, pin 4	FMC FAN enable	
FMC_PG_C2M	FMC J2, pin D1	FMC control signals	refer to current SC CPLD firmware for functionality
FMC_PG_M2C	FMC J2, pin F1		
FMC_PRSNT_M2C_L	FMC J2, pin H2		
FMC_SCL	FMC J2, pin C30	FMC I ² C	I ² C connected to FPGA
FMC_SDA	FMC J2, pin C31		
FMC_TCK	FMC J2, pin D29	FMC JTAG	refer to current SC CPLD firmware for functionality

FMC_TDI	FMC J2, pin D30		
FMC_TDO	FMC J2, pin D31		
FMC_TMS	FMC J2, pin D33		
FMC_TRST	FMC J2, pin D34		
DONE	FPGA bank 0, pin J7	FPGA configuration signal	PL configuration completed
PROGRAM_B	FPGA bank 0, pin P6		PL configuration reset signal
LED1	Green LED D11	LED status signal	refer to current SC CPLD firmware for functionality
FPGA_IIC_OE	FPGA bank 14, pin F25	SC CPLD works as I ² C switch with the FPGA as I ² C-Master and on-board peripherals as I ² C-Slaves	I ² C output enable
FPGA_IIC_SCL	FPGA bank 14, pin G26		I ² C clock line
FPGA_IIC_SDA	FPGA bank 14, pin G25		I ² C data line
EN_1V8	DC-DC U20, pin 27	Power control	enable signal DC-DC U20
PG_1V8	DC-DC U20, pin 28		power good signal DC-DC U20
EN_3V3FMC	DC-DC U15, pin 27		enable signal DC-DC U15
PG_3V3	DC-DC U15, pin 28		power good signal DC-DC U15
EN_FMC_VADJ	DC-DC U7, pin 52		enable signal DC-DC U7
PG_FMC_VADJ	DC-DC U7, pin 46		power good DC-DC U7
VID0_FMC_VADJ, VID1_FMC_VADJ, VID2_FMC_VADJ	DC-DC U7, pin 45, 44, 43		DCDC U7 power selection pin
VID0_FMC_VADJ_CTRL, VID1_FMC_VADJ_CTRL, VID2_FMC_VADJ_CTRL	DIP switch S1-2, DIP switch S1-3, DIP switch S1-4		Power selection of FMC_VADJ, forwarded to DCDC U7
LTM_1V5_RUN	DC-DC U3, pin F5		enable signals of DCDC U3, U4 (LTM4676) refer to current SC CPLD firmware for functionality
LTM_4V_RUN	DC-DC U3, pin F5		
LTM_SCL	DC-DC U3 / U4, pin E6	DCDC U3, U4 (LTM4676) I ² C	I ² C Address U3: 0x40
LTM_SDA	DC-DC U3 / U4, pin D6		I ² C Address U4: 0x4F I ² C interface of LTM4676 ICs also accessible through header J10
LTM1_ALERT	DC-DC U4, pin E5	DCDC U3, U4 (LTM4676) control, active low	refer to current SC CPLD firmware for functionality
LTM2_ALERT	DC-DC U3, pin E5		
LTM_1V_IO0	DC-DC U4, pin E4		
LTM_1V_IO1	DC-DC U4, pin F5		
LTM_1V5_4V_IO0	DC-DC U3, pin E4		
LTM_1V5_4V_IO1	DC-DC U3, pin F4		

System Controller CPLD I/O pins

DDR3 SDRAM ECC SO-DIMM Socket

The TEF1001 board supports additional DDR3 **ECC** SO-DIMM via 204-pin socket U2. The DDR3 memory interface has a 64bit wide databus and is routed to the FPGA banks 32, 33 and 34.

The reference clock signal for the DDR3 interface is generated by the 200.0000MHz MEMS oscillator U1 and is applied to the FPGA bank 33.

There is also a I²C interface between the System Controller CPLD U5 and the DDR3 ECC SO-DIMM memory socket U2.

I ² C Interface	Schematic net names	Connected to	I ² C Address	Notes
DDR3 SODIMM, U2	'DDR3_SDA', pin 200 'DDR3_SCL', pin 202	SC CPLD U5, pin 42 SC CPLD U5, pin 43	module dependent	-

DDR3 SODIMM socket I²C interface



It is important to use SO-DIMMs which provide ECC functionality. SO-DIMMs without ECC are not compatible with this board.

Quad SPI Flash Memory

A 256 Mbit (32 MByte) Quad SPI Flash Memory (Micron N25Q256A, U12) is provided for FPGA configuration file storage. After configuration process completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency. The memory can be accessed indirectly by the FPGA JTAG port (J9) by implementing the functional logic for this purpose inside the FPGA.

Quad SPI Flash memory interface is connected to the FPGA bank 14, QSPI clock is provided by FPGA config bank 0.

Signal Name	QSPI Flash Memory U12 Pin	FPGA Pin
FLASH_QSPI_CS	S, Pin 7	Bank 14, Pin C23
FLASH_QSPI_D00	DQ0, Pin 15	Bank 14, Pin B24
FLASH_QSPI_D01	DQ1, Pin 8	Bank 14, Pin A25
FLASH_QSPI_D02	DQ2, Pin 9	Bank 14, Pin B22
FLASH_QSPI_D03	DQ3, Pin 1	Bank 14, Pin A22
FPGA_CFG_CCLK	C, Pin 16	Bank 0, Pin C8

Quad SPI interface signals and connections



SPI Flash QE (Quad Enable) bit must be set to high or FPGA is unable to load its configuration from flash during power-on. By default this bit is set to high at the manufacturing plant.

Programmable Clock Generator

There is a Silicon Labs I²C programmable quad PLL clock generator on-board (Si5338A, U13) to generate various reference clocks for the module.

Si5338A Pin	Signal Name / Description	Connected to	Direction	Note
IN1	-	not connected	Input	not used
IN2	-	GND	Input	not used
IN3	Reference input clock	U3, pin 3	Input	25.000000 MHz oscillator U14, Si8208AI
IN4	-	GND	Input	I ² C slave device address LSB
IN5	-	not connected	Input	not used
IN6	-	GND	Input	not used
SCL	PLL_SCL	SC CPLD U5, pin 8	Input / Output	I ² C interface muxed to FPGA
SDA	PLL_SDA	SC CPLD U5, pin 2	Input / Output	
CLK0A	CLK0_P	U6, G24	Output	Clock to PL bank 14

CLK0B	CLK0_N	U6, F24		
CLK1A	MGTCLK_5338_P	U6, H6	Output	Clock to MGT bank 115, AC decoupled
CLK1B	MGTCLK_5338_N	U6, H5		
CLK2A	CLK1_P	U6, G22	Output	Clock to PL bank 14
CLK2B	CLK1_N	U6, F23		
CLK3A	CLK2_P	U6, D23	Output	Clock to PL bank 14
CLK3B	CLK2_N	U6, D24		

Programmable quad PLL clock generator inputs and outputs

Oscillators

The FPGA module has following reference clocking sources provided by on-board oscillators and FMC connector J2:

Clock Source	Frequency	Signal Schematic Name	Clock Destination	Notes
U14, SiT8208AI	25.000000 MHz	CLK	Si5338A PLL U13, pin 3 (IN3)	-
U1, DSC1123DL5	200.0000 MHz	DDR3_CLK_P	FPGA bank 33, pin AB11	Enable by SC CPLD U5, pin 30
		DDR3_CLK_N	FPGA bank 33, pin AC11	Signal: '200MHzCLK_EN'
FMC Connector J2	-	GBTCLK0_M2C_P, Pin J2-D4	FPGA bank 116, pin D6	reference clock to MGT bank 116
		GBTCLK0_M2C_N, Pin J2-D5	FPGA bank 116, pin D5	
	-	GBTCLK1_M2C_P, Pin J2-B20	FPGA bank 116, pin F6	reference clock to MGT bank 116
		GBTCLK1_M2C_N, Pin J2-B21	FPGA bank 116, pin F5	
	-	CLK0_M2C_P, Pin J2-H4	FPGA bank 15, pin H17	reference clock to PL bank 15
		CLK0_M2C_N, Pin J2-H5	FPGA bank 15, pin H18	
	-	CLK1_M2C_P, Pin J2-G2	FPGA bank 15, pin G17	reference clock to PL bank 15
		CLK1_M2C_N, Pin J2-G3	FPGA bank 15, pin G18	
	-	CLK2_BIDIR_P, Pin J2-K4	FPGA bank 13, pin P23	reference clock to PL bank 13 bidirectional clock line
		CLK2_BIDIR_N, Pin J2-K5	FPGA bank 13, pin N23	
	-	CLK3_BIDIR_P, Pin J2-J2	FPGA bank 13, pin R22	reference clock to PL bank 13 bidirectional clock line
		CLK3_BIDIR_N, Pin J2-J3	FPGA bank 13, pin R23	

Reference clock signals

On-board LEDs

LED	Color	Signal Schematic name	Connected to	Description and Notes
D1	Green	FPGA_LED1_VT	FPGA bank 13, pin K25	LEDs D1 to D10 are available to user. LED voltages are translated from FPGA bank 13 and 14 VCCO voltage FMC_VADJ to 3V3.
D2	Green	FPGA_LED2_VT	FPGA bank 13, pin K26	
D3	Green	FPGA_LED3_VT	FPGA bank 13, pin P26	
D4	Green	FPGA_LED4_VT	FPGA bank 13, pin R26	
D5	Green	FPGA_LED5_VT	FPGA bank 13, pin N16	
D6	Green	FPGA_LED6_VT	FPGA bank 14, pin J26	
D7	Green	FPGA_LED7_VT	FPGA bank 14, pin H26	

D8	Green	FPGA_LED8_VT	FPGA bank 14, pin E26	refer to current CPLD firmware for LED functionality
D9	Green	FPGA_LED9_VT	FPGA bank 14, pin A24	
D10	Green	FPGA_LED10_VT	FPGA bank 15, pin F19	
D11	Green	LED1	System Controller CPLD, bank 0, pin 76	

On-board LEDs description

Configuration DIP-switch

There is one 4-bit DIP-switches S1 present on the TEB0911 board to configure options and set parameters. The following section describes the functionalities of the particular switches.

Table below describes the functionalities of the switches of DIP-switches S3 and S4 at their each positions:

DIP-switch S3	Signal Schematic Name	Connected to	Functionality	Notes
S1-1	JTAG_EN	SC CPLD U5, bank 1, pin 82	enables JTAG interface of SC CPLD U5 in ON-position	SC CPLD programmable through JTAG header J8
S1-2	VID0_FMC_VADJ_CT RL	SC CPLD U5, bank 1, pin 71	set 3bit code to adjust FMC_VADJ voltage	The FMC_VADJ voltage is provided by DCDC U7 EN5365QI, the voltage can be adjusted from 0.8V to 3.3V in 7 steps: Set DIP-switches as bit pattern "S1-4 S1-3 S1-2: FMC_VADJ": 0 0 0 : 3.3V 0 0 1 : 2.5V 0 1 0 : 1.8V 0 1 1 : 1.5V 1 0 0 : 1.25V 1 0 1 : 1.2V 1 1 0 : 0.8V 1 1 1 : Reserved
S1-3	VID1_FMC_VADJ_CT RL	SC CPLD U5, bank 1, pin 63		
S1-4	VID2_FMC_VADJ_CT RL	SC CPLD U5, bank 1, pin 62		

DIP-switch S1 functionality description

Push Buttons

There is one push buttons available to the user connected to the SC CPLD U5:

Button	Connected to	Function	Notes
S2	SC CPLD U5, pin 77	Global board Reset	Refer to documentation of current SC CPLD firmware for more details.

On-board Push Button

Power and Power-On Sequence

Power Consumption

The maximum power consumption of a module mainly depends on the design running on the FPGA.

Xilinx provide a power estimator excel sheets to calculate power consumption. It's also possible to evaluate the power consumption of the developed design with Vivado. See also Trenz Electronic Wiki [FAQ](#).

Power Input	Typical Current
12V VIN	TBD*

Typical power consumption

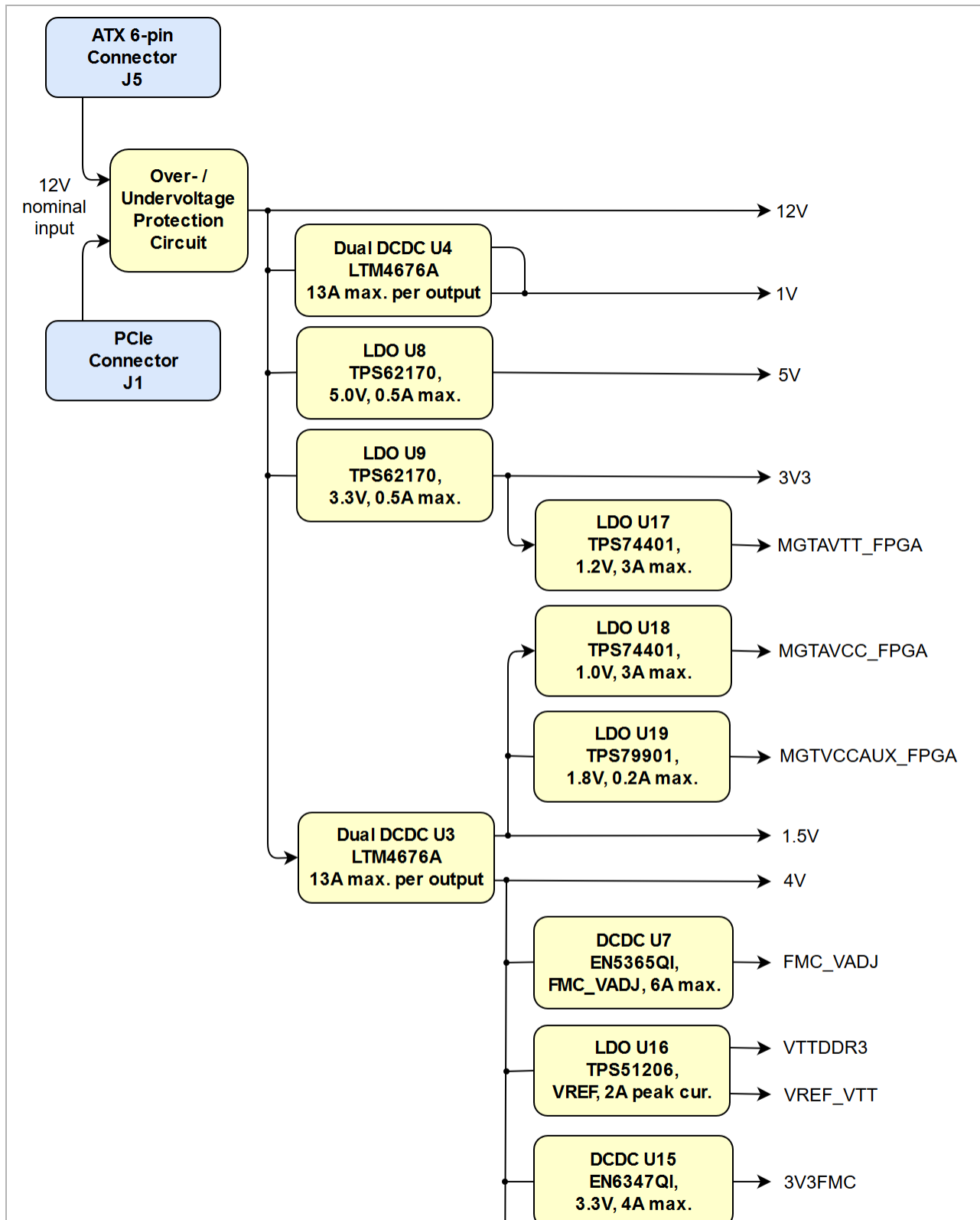
* TBD - To Be Determined soon with reference design setup.

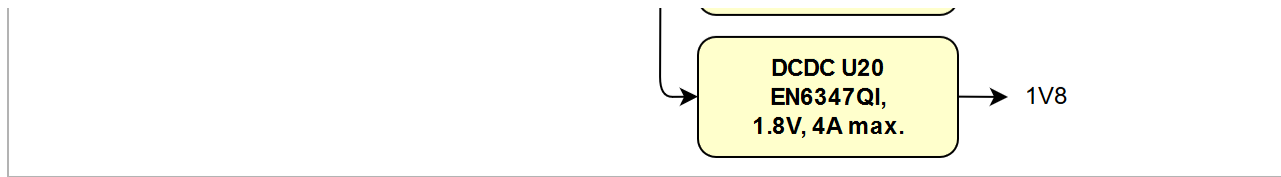
It is recommended to connect the ATX connector J5 to a 12V power supply source with minimum current capability of 6A to provide a sufficient power source to the board. Only one power source is needed at the same time, the system disconnects automatically PCIe power supply from PCIe edge connector J1 if the board is powered by the ATX connector J5.



To avoid any damage to the module, check for stabilized on-board voltages should be carried out (i.e. power good and enable signals) before powering up any FPGA's I/O bank voltages VCCO_x. All I/Os should be tri-stated during power-on sequence.

Power Distribution Dependencies





Power Distribution

Power-On Sequence

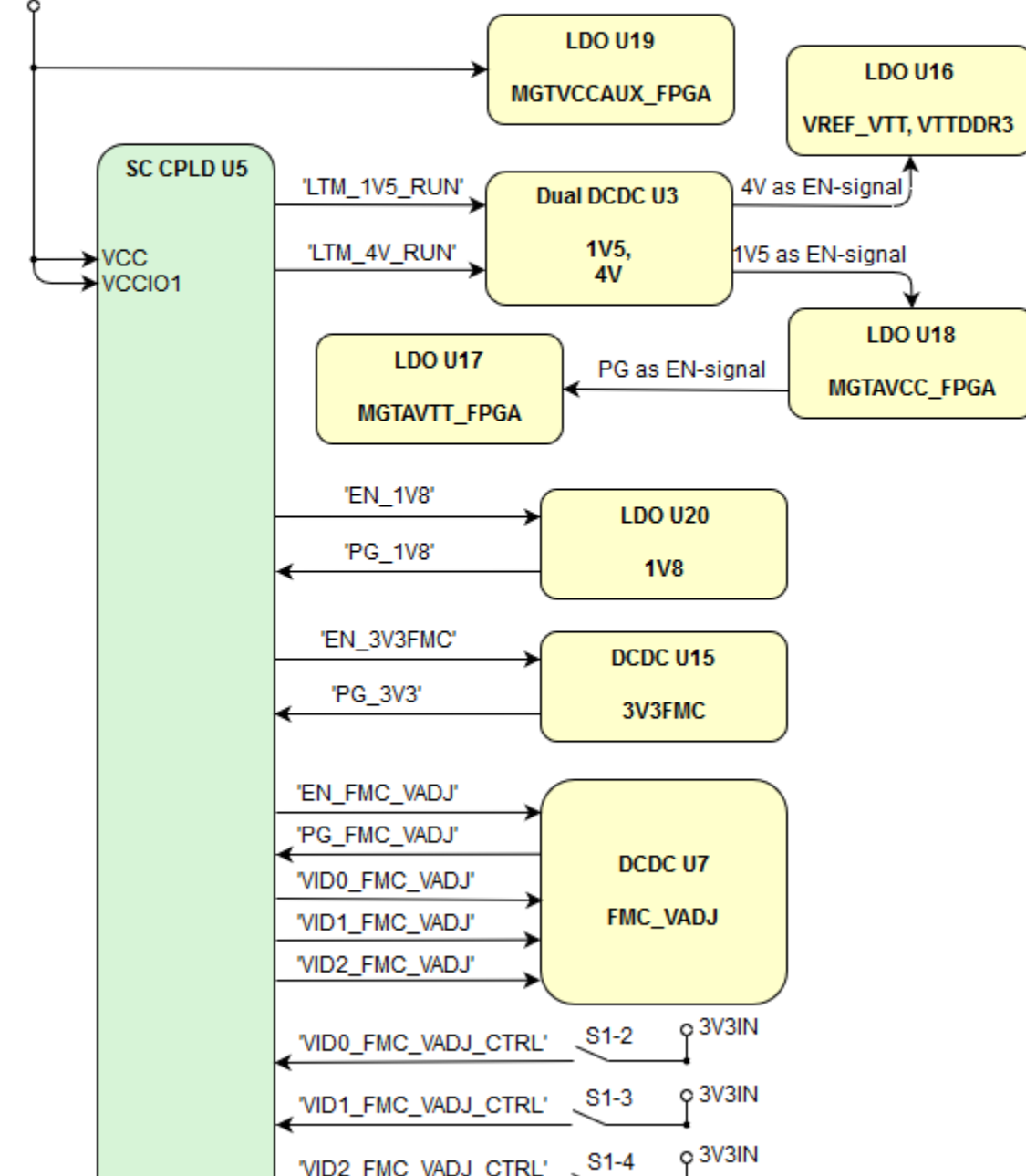
The TEF1001 board meets the recommended criteria to power up the Xilinx FPGA properly by keeping a specific sequence of enabling the on-board DC-DC converters dedicated to the particular functional units of the FPGA chip and powering up the on-board voltages. Some of the voltages are handled by the System Controller CPLD using "Power good"-signals from the voltage regulators:

Following diagram clarifies the sequence of enabling the particular on-board voltages, which will power-up in descending order as listed in the blocks of the diagram:

12V (external power supply) as EN-signal

Dual DCDC U4, 1V
LDO U8, 5V
LDO U9, 3V3

3V3 (U9) as EN-signal





Power Sequence

Bank Voltages

Bank	Schematic Name	Voltage	Range	Notes
0	1V8	1.8V	-	Config bank 0 fixed to 1.8V
12	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
13	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
14	1V8	1.8V	HR: 1.2V to 3.3V	PL bank 14 fixed to 1.8V
15	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
16	VIO_B_FMC	user	HR: 1.2V to 3.3V	PL bank 16 fixed to 1.8V
32	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
33	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
34	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
115	MGTAVCC_FPGA	1.0V	MGT bank supply voltage	MGT banks with Xilinx GTX transceiver units
116	MGTVCCAUX_FPGA	1.8V	MGT bank auxiliary supply voltage	
	MGTAVTT_FPGA	1.2V	MGT bank termination circuits voltage	

Board I/O bank voltages

Power Rails

Connector / Pin	Voltage	Direction	Notes
J4, pin 2	12V	Output	4-wire PWM fan connector supply voltage
J6, pin 2	5V	Output	Cooling fan M1 supply voltage
J8, pin 6	3V3	Output	VCCIO CPLD JTAG
J9, pin 2	1V8	Output	VCCIO FPGA JTAG
J2, pin C35 / C37	12V	Output	FMC supply voltage
J2, pin D32	3V3	Output	VCCIO FMC
J2, pin D36 / D38 / D39 / D40	3V3FMC	Output	VCCIO FMC
J2, pin H1	VREF_A_M2C	Input	VREF voltage for bank 13 / 15
J2, pin K1	VREF_B_M2C	Input	VREF voltage for bank 16
J2, pin J39 / J40	VIO_B_FMC	Input	PL I/O voltage bank 16 (VCCO)
J2, pin H40 / G39 / F40 / E39	FMC_VADJ	Output	PL I/O voltage bank 12 / 13 / 15 (VCCO)
J1, pin B1 / B2 / B3 / A2 / A3	12V_input_B	Input	12V main power supply from PCIe connector
J5, pin 1 / 2 / 3	12V_input_A	Input	Main power supply connector

Board power rails

Technical Specifications

Absolute Maximum Ratings

Parameter	Min	Max	Units	Reference Document
VIN supply voltage	-0.3	20	V	TPS6217 datasheet Note: voltage limitations are not valid for connected FMC module and/or FPGA FAN
Supply voltage for HR I/O banks (VCCO)	-0.500	3.600	V	Xilinx datasheet DS182
Supply voltage for HP I/O banks (VCCO)	-0.500	2.000	V	Xilinx datasheet DS182
I/O input voltage for HR I/O banks	-0.500	VCCO + 0.500	V	Xilinx datasheet DS182
I/O input voltage for HP I/O banks	-0.500	VCCO + 0.500	V	Xilinx datasheet DS182
Reference Voltage pin (VREF)	-0.500	2	V	Xilinx datasheet DS182
Differential input voltage	-0.5	2.625	V	Xilinx datasheet DS182
I/O input voltage for SC CPLD U5	-0.5	3.75	V	Lattice MachXO2 Family datasheet
GTX transceiver reference clocks absolute input voltage	-0.500	1.320	V	Xilinx datasheet DS182
GTX transceiver receiver (RXP/RXN) and transmitter (TXP/TXN) absolute input voltage	-0.500	1.260	V	Xilinx datasheet DS182
Voltages on LTM4676 I ² C pins (LTM_SCL, LTM_SDA), header J10	-0.3	5.5	V	LTM4676A datasheet
Storage temperature	-40	+100	°C	SML-P11 LED datasheet

Module absolute maximum ratings



Assembly variants for higher storage temperature range are available on request.

Recommended Operating Conditions

Parameter	Min	Max	Units	Reference Document
VIN supply voltage	11.4	12.6	V	12V nominal, ANSI/VITA 57.1 power specification for FMC connector
Supply voltage for HR I/O banks (VCCO)	1.140	3.465	V	Xilinx datasheet DS182
Supply voltage for HP I/O banks (VCCO)	1.140	1.890	V	Xilinx datasheet DS182
I/O input voltage for HR I/O banks	-0.500	VCCO + 0.20	V	Xilinx datasheet DS182
I/O input voltage for HP I/O banks	-0.500	VCCO + 0.20	V	Xilinx datasheet DS182
Differential input voltage	-0.2	2.625	V	Xilinx datasheet DS182
I/O input voltage for SC CPLD U5	-0.3	3.6	V	Lattice MachXO2 Family datasheet
Voltages on LTM4676 I ² C pins (LTM_SCL, LTM_SDA), header J10	0	3.3V	V	LTM4676A datasheet
Board Operating Temperature Range ^{1), 2)}	-40	85	°C	board operating temperature range limited by FPGA SoC and on-board peripherals

Recommended Operating Conditions

1) Temperature range may vary depending on assembly options

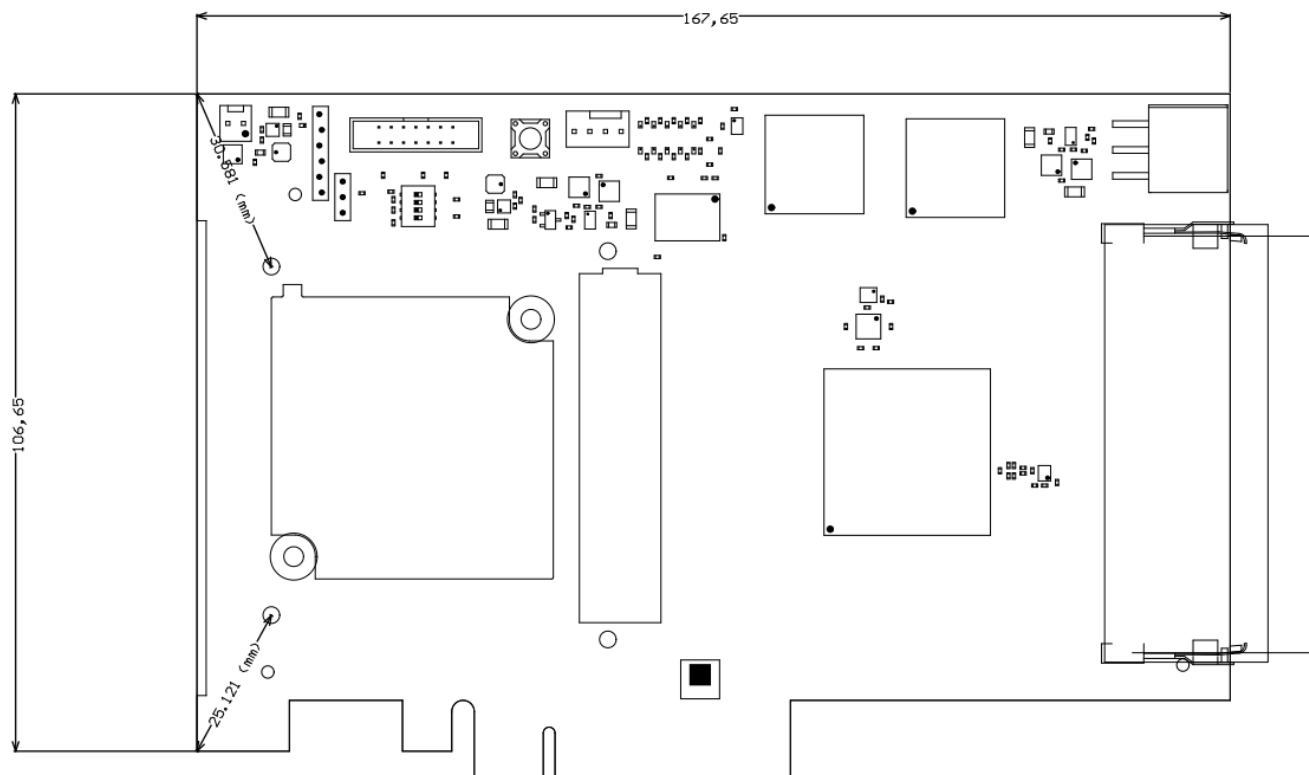
2) The operating temperature range of the FPGA soC and on-board peripherals are junction and also ambient operating temperature ranges

Board operating temperature range depends also on customer design and cooling solution. Please contact us for options.



Please check also Xilinx datasheet [DS182](#) for complete list of absolute maximum and recommended operating ratings.

Physical Dimensions



Physical dimensions drawing

Variants Currently In Production

Trenz shop TEF1001 overview page	
English page	German page

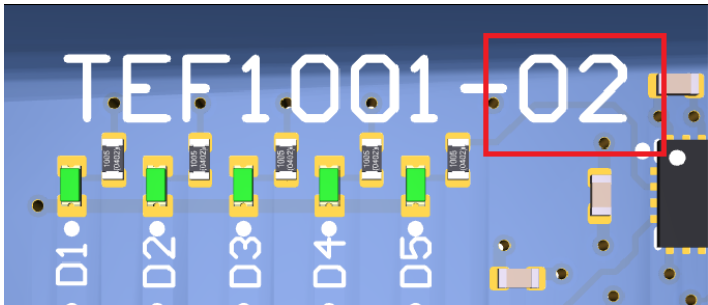
Trenz Electronic Shop Overview

Revision History

Hardware Revision History

Date	Revision	Notes	PCN	Documentation Link
-	02	current available board revision	-	-
-	01	First production release	PCN-20180524 TEF1001-01	TEF1001-01

Hardware Revision History



Hardware Revision Number

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.

Document Change History

Date	Revision	Authors	Description
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			• update picture
Error rendering macro 'page-info' Ambiguous method overloading for method jdk.proxy241.\$Proxy3496#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	Error rendering macro 'page-info' Ambiguous method overloading for method jdk.proxy241.\$Proxy3496#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] Unknown macro: 'metadata'	Error rendering macro 'page-info' Ambiguous method overloading for method jdk.proxy241.\$Proxy3496#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	
2018-10-24	v.41	Guillermo Herrera	• Initial document

Document change history

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Ambiguous method overloading for method `jdk.proxy241.$Proxy3496#hasContentLevelPermission`. Cannot resolve which method to invoke for `[null, class java.lang.String, class com.atlassian.confluence.pages.Page]` due to overlapping prototypes between: `[interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]` `[interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]`